规格书编号

SPEC NO :

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDBF07011A24 SMD-24

PREPARED 编 制： CHECKED 审 核：

APPROVED 批 准： D A T E 日 期：2012-2-21

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子股份有限公司

Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

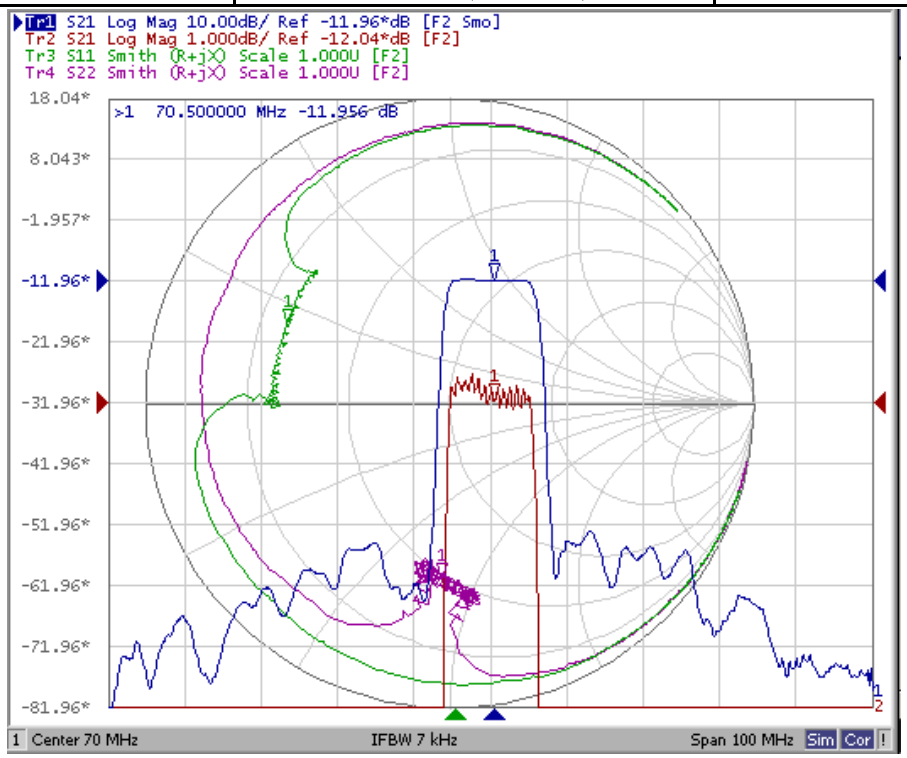
This specification shall cover the characteristics of SAW filter HDBF07011A24.

2. ELECTRICAL SPECIFICATION

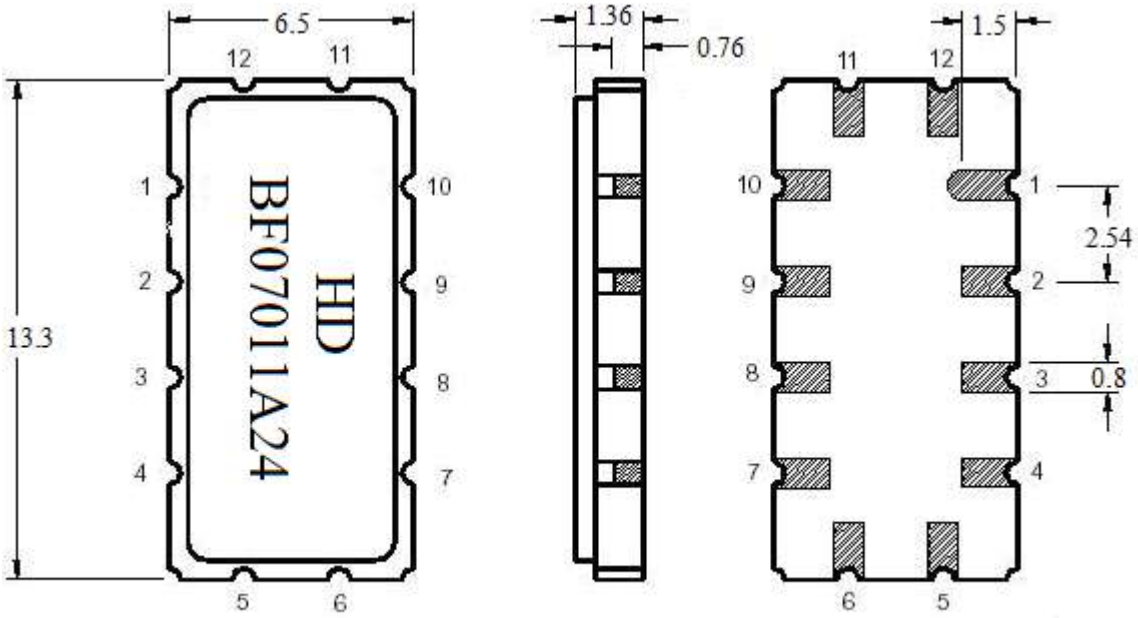
Max Incident Power in Passband	10 dBm
Max voltage between any 2 terminals	30 VDC
Storage Temperature Range	-40 to +85 ℃
Operating Temperature Range	-40 to +85 ℃

Electronic Characteristics

Parameter	Min	Typ	Max	Units
Center Frequency	69.8	70	70.2	MHz
Insertion Loss		12	13	dB
-1dB Bandwidth		11		MHz
-3dB Bandwidth		11.78		MHz
-6dB Bandwidth		12.46		MHz
-40dB Bandwidth		14		MHz
Passband Variation		0.5	1.0	dB
Absolute delay		1.2		us
Ultimate Rejection	38	40		dB
Material Temperature coefficient		6.02		KHz/℃
Ambient Temperature		25		℃
Package		SMD-24(13.3*6.5)		

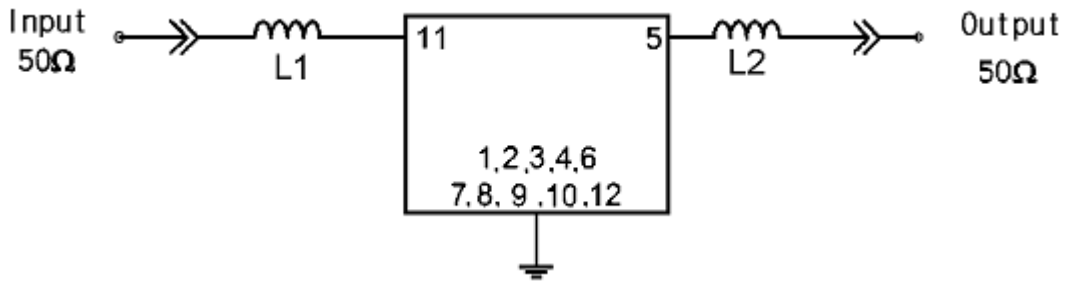


3. DIMENSION



Pin Configuration	
11	Input
5	Output
Other	Ground

4. TEST CIRCUIT



L1=250nH, L2=250nH

* Component values may vary due to actual PCB layout and parasitics.

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85℃ for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-2 Low temperature exposure

Subject the device to -20℃ for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-3 Temperature cycling

Subject the device to a low temperature of -40℃for 30 minutes. Following by a high temperature of +80℃ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260℃ ±10℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

5-5 Solderability

Subject the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

5-8 Lead fatigue

5-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

5-8-2 Bending test

Lead shall be subject to withstand against 90℃ bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

6. REMARK

7.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

7.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

7.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.